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with Amendment 1
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Specification for Base Materials for High Speed/ High Frequency Applications

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December 2011

A standard developed by IPC

Association Connecting Electronics Industries



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Developed by the High Speed/High Frequency Base Materials
Subcommittee (D-23) of the High Speed/High Frequency Committee
(D-20) of IPC

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modifications to noted errata.

Users of this publication are encouraged to participate in the
development of future revisions.

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